

# MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material	MF - MSMF
Product Line	Multifuse
Revision Date	April 15, 2005
Revision	A
RoHS Compliant	Yes



No.	Breakdown of part (e.g. Lead, Ceramic body, coating, plating, additive)	Material/substance name (e.g. Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0008432	1333-86-4	3.77%	3.77%
2	Copper plating	Copper	0.0016212		7.24%	7.24%
3	Foil	Copper	0.0107250	7440-50-8	47.90%	50.42%
		Nickel	0.0005645	7440-02-0	2.52%	
4	PCB Foil	Copper	0.0013630	7440-50-8	6.09%	6.09%
5	Polymer	Polyethylene Homopolymer	0.0007470	9002-88-4	3.34%	3.34%
		Proprietary Additives	0.0000010			
6	Prepreg	Epoxy	0.0038512		17.20%	28.66%
		Glass fiber	0.0025672		11.47%	
7	Packing-Carrier Tape	Polystyrene	N/A	9003-53-6		
		Polyethylene Homopolymer	N/A	9002-88-4		
8	Packing-Cover Tape	Polyethylene terephthalate	N/A	25038-59-9		
		Polyethylene Homopolymer	N/A	9002-88-4		
9	Soldering plating	Nickel	0.0001066		0.48%	0.48%
10	Soldering plating	Gold	0.0000013		0.01%	0.01%

Total weight (grams)	0.0223912	Total	100%	100%
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